

**ABSTRACT**

A semiconductor component includes a semiconductor die, a low k polymer layer on the die and redistribution conductors on the polymer layer. The component also 10 includes bonding pads on the conductors with a metal stack construction that includes a conductive layer, a barrier/adhesion layer and a non-oxidizing layer. The bonding pads facilitate wire bonding to the component and the formation of reliable wire bonds on the component. A 15 method for fabricating the component includes the steps of forming the conductors and bonding pads using electroless deposition. The component can be used to fabricate electronic assemblies such as modules, packages and printed circuit boards.

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